

SMBF

RoHS
COMPLIANT



Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Built-in strain relief, ideal for automated placement
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed
260°C/10 seconds at terminals

Mechanical Data

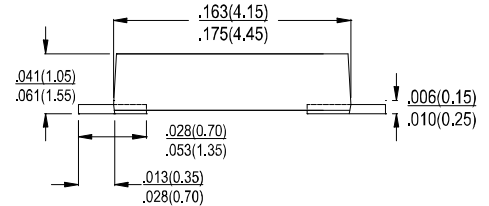
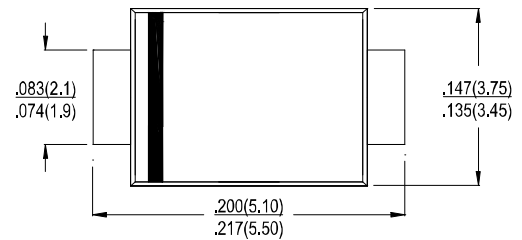
Case : Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.0020 ounce, 0.056 grams



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	SS								UNITS
		52BF	54BF	545BF	56BF	58BF	510BF	515BF	520BF	
Maximum repetitive peak reverse voltage	V_{RRM}	20	40	45	60	80	100	150	200	V
Maximum RMS voltage	V_{RMS}	14	28	31.5	42	56	70	105	140	V
Maximum DC blocking voltage	V_{DC}	20	40	45	60	80	100	150	200	V
Maximum average forward rectified current at $T_L=100^\circ\text{C}$	$I_{(AV)}$	5.0								A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	120.0								A
Maximum instantaneous forward voltage at 5.0A	V_F	0.55		0.70	0.85		0.95		V	
Maximum DC reverse current at rated DC blocking voltage $T_A=25^\circ\text{C}$ $T_A=100^\circ\text{C}$	I_R	0.2 10			0.05 5				mA	
Typical thermal resistance	R_{qJA}	85.0								°C/W
Operating junction temperature range	T_J	-55 to +150								°C
Storage temperature range	T_{STG}	-55 to +150								°C

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

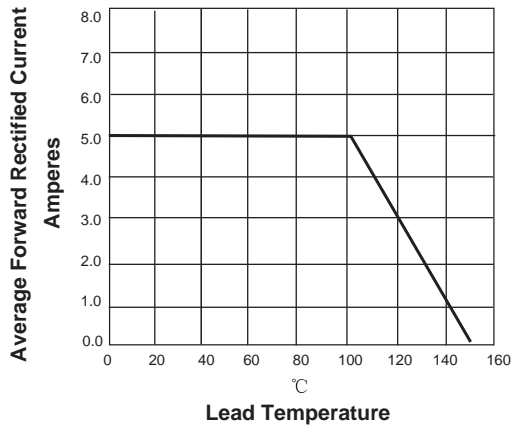


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

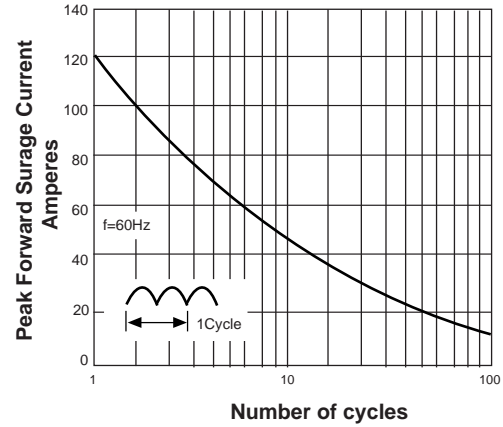


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

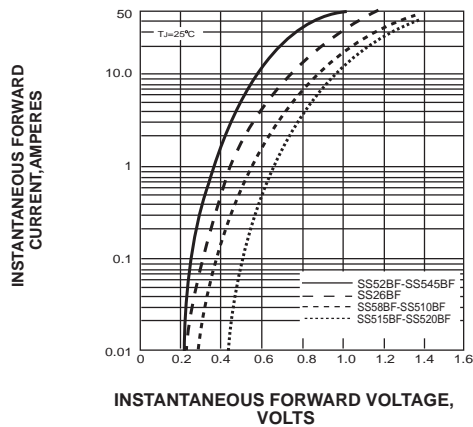
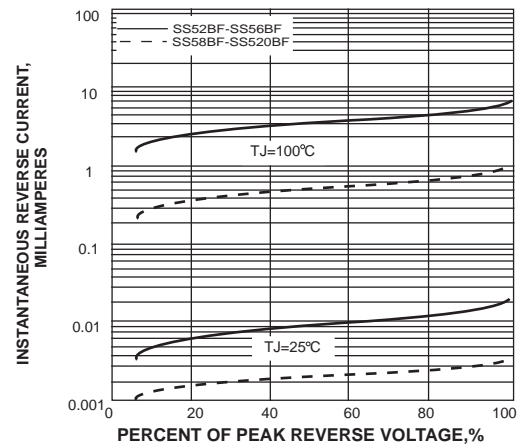
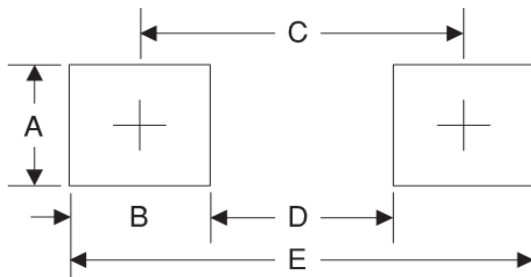


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

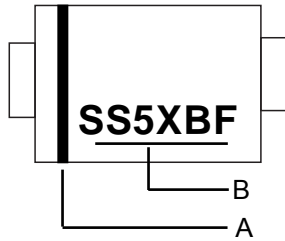


Suggested Pad Layout



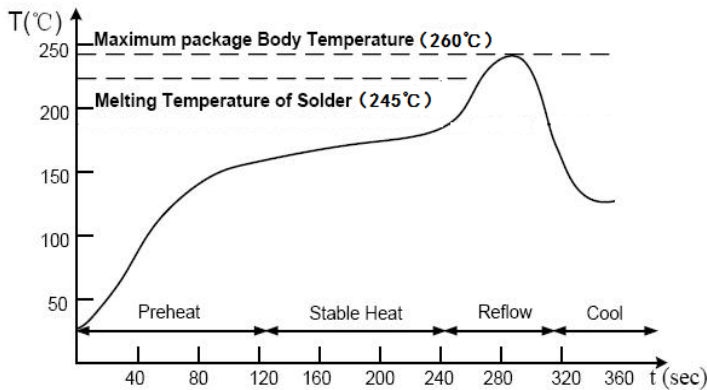
Symbol	Unit (mm)	Unit (inch)
A	2.30	0.091
B	2.00	0.078
C	4.10	0.161
D	2.10	0.083
E	6.10	0.240

Marking



Symbol	Explanation
A	Color Band Denotes Cathode
B	Product Name, X : 2.4.....20

Suggested Soldering Temperature Profile

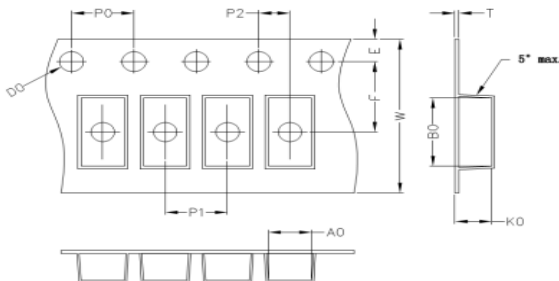


Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 260°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Carrier Dimension(mm)



A0	B0	K0	D0	E	F
3.80	5.75	1.40	1.55	1.75	5.50
P0	P1	P2	T	W	Tolerance
4.0	4.0	2.0	0.25	12	0.1

Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
SMBF	11'	278	3	285	6	355*310*310	48
	13'	330	5	338	10	365*365*360	80